

AMPMODU System – Foil, Multiple Crimp Pin Contact

Technical Features

Contact Material:

CuSn4

Contact Finish:

pre-tin plated,
selective gold plated on request

Contact Resistance

(New State):

CuSn4: $\leq 3 \text{ m}\Omega$

Total Temperature max. :*

-40 °C to +120 °C

Mating Cycles:

dependant of plating thicknesses,
see product specification

Insertion Force:

Standard: 4.2 N max.
High Pressure: 10.2 N max.

Extraction Force:

Standard: 0.4 N min.
High Pressure: 0.8 N min.

Retention Force

(from Housing):

- without second locking device
> 13 N
depends on housing material

Conductor Thickness:

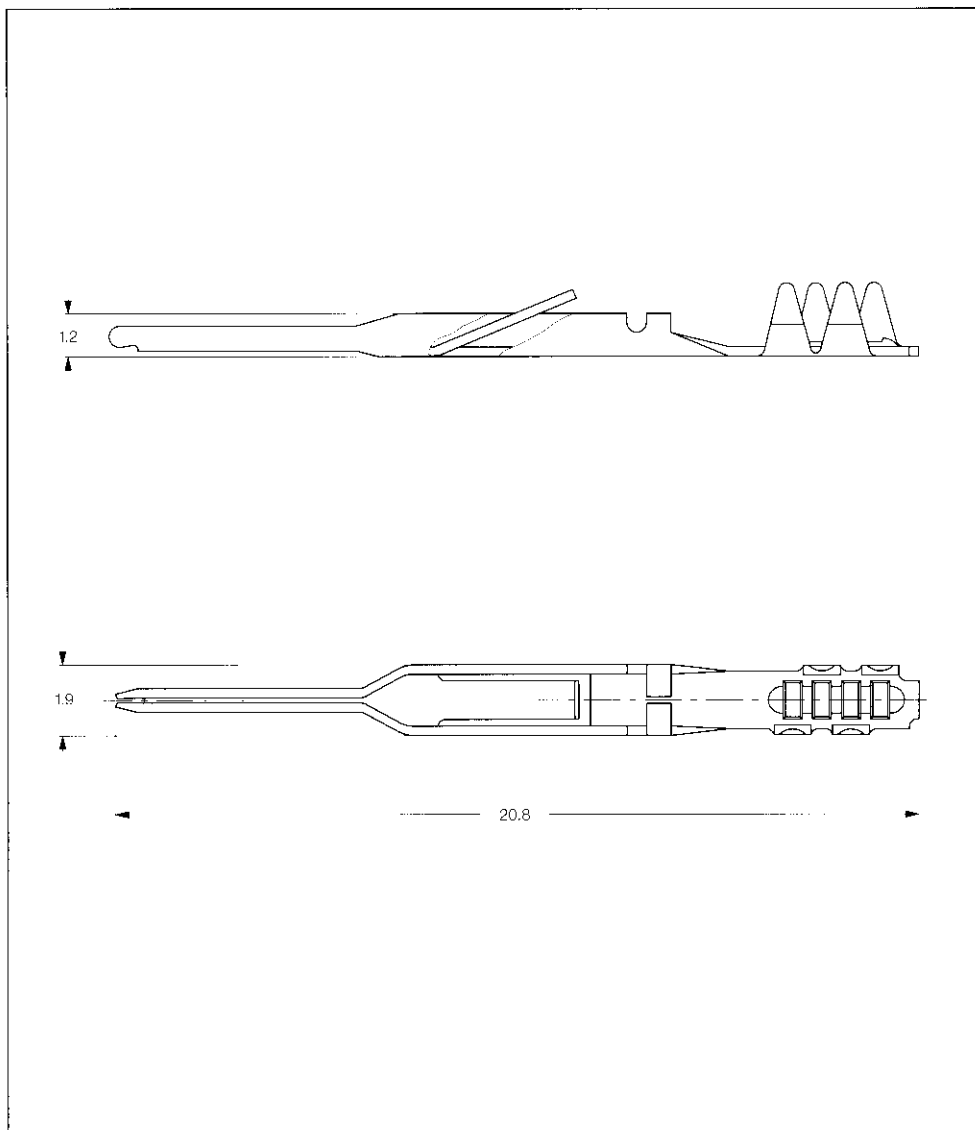
4-200 μm

Product Specification:

108-xxxxx

Application Specification:

114-16015



Pin Contacts

Wire Size Range* (mm ²)	Insulation Diameter*		Material and Finish**	Part Numbers					
	FLK (mm)	FLR (mm)		Strip Form	Packaging Unit	Loose-Piece	Packaging Unit	Applicator	Hand Tool
-	-	-	5	88117-2	15,000	-	-	224910	-
-	-	-	2	88117-3	15,000	-	-	-	90273-5
-	-	-	3	88117-4	15,000	-	-	-	-
-	-	-	1	88117-5	15,000	-	-	318619	-

*) Depending on Foil

**** Material and Finish:**

- 1 = Tin on mating area, crimp area tin plated
- 2 = 0.38 μm gold on mating area, crimp area tin plated
- 3 = 0.76 μm gold on mating area, crimp area tin plated
- 5 = 1.27 μm gold on mating area, crimp area tin plated